

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

Claim 1 (original): A communication device comprising a RFID part fixed on an insulation substrate, wherein said insulation substrate is surface-mountable on a circuit board.

Claim 2 (original): A communication device comprising a RFID part fixed on a surface-mount chip antenna, wherein an antenna terminal of said RFID part is electrically connected to a terminal of said surface-mount chip antenna.

Claim 3 (original): The communication device according to claim 2, wherein said surface-mount chip antenna is a coil antenna.

Claim 4 (currently amended): The communication device according to any one of claims ~~1-3~~1-2, wherein fixture is achieved by resin molding.

Claim 5 (currently amended): The communication device according to any one of claims ~~2-4~~1-2, wherein electrical connection is achieved by wire bonding or flip-chip mounting.

Claim 6 (currently amended): The communication device according to any one of claims ~~1-5~~1-2, said insulation substrate or said surface-mount chip antenna having a recess, wherein said RFID part is disposed in said recess.

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Claim 7 (currently amended):        The communication device according to any one of claims ~~1-7~~1-2, wherein said communication device is a communication device placed on an electronic device or other products completed through multiple process steps, said RFID part storing historical information about said process steps.

Claim 8 (currently amended):        A    communication    device    package comprising a taping material or a bulk casing configured to package said communication device according to any one of claims ~~1-7~~1-2.